

ON Semiconductor			6/1/2021	
Base Part		FDB047N10	HF	
Orderable Part		FDB047N10	Total weight (mg)	1485.099
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	12.3	Silicon (Si)	7440-21-3	100
Die Attach	7.331	Silver (Ag)	7440-22-4	1.5
		Lead (Pb)	7439-92-1	93.5
Lead Frame	860.318	Tin (Sn)	7440-31-5	5
		Tin (Sn)	7440-31-5	0.12
		Nickel (Ni)	7440-02-0	0.05
Mold Compound-Black	595	Copper (Cu)	7440-50-8	99.83
		Metal Hydroxide	proprietary data	3.5
		Ortho Cresol Novolac Resin	29690-82-2	8
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO ₂)	60676-86-0	80
Plating	5.52	Phenolic Resin (Novolac)	9003-35-4	8
Wire Bond - Al	4.63	Tin (Sn)	7440-31-5	100
		Aluminum (Al)	7429-90-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				